



Docket No.: 42P18770

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Koning et al.

Application No.: 10/815,291

Filed: March 30, 2004

For: MICROELECTRONIC PACKAGES
INCLUDING NANOCOMPOSITE
DIELECTRIC BUILD-UP MATERIALS AND
NANOCOMPOSITE SOLDER RESIST

Examiner: Luan C. Thai

Art Unit: 2891

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUBMISSION OF REPLACEMENT DRAWINGS

Sir:

Submitted herewith are replacement drawings, Figures 1-7 (4 sheets). No new matter has been added. Applicants respectfully request approval of the enclosed replacement drawings for the above-identified application.

Respectfully submitted,

BLAKELY SOKOLOFF TAYLOR & ZAFMAN, LLP

Date: 6-29-06

Todd M. Becker
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FIRST CLASS CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

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